



台燿科技股份有限公司

Taiwan Union Technology Corporation

TEST REPORT

CLIENT: IPC Validation Services
3000 Lakeside Drive
Suite 105N
Bannockburn, IL 60015 USA
Attention: Mr. Randy Cherry
+1-847-597-5606

TEST ITEMS: Peel Strength, Volume Resistivity, Surface Resistivity, Moisture Absorption, Dielectric Breakdown, Permittivity @ 1 MHz, Loss Tangent @ 1 MHz, Flexural Strength, Arc Resistance, Thermal Stress, Electric Strength, Flammability, Glass Transition Temperature, Decomposition Temperature, CTE (TMA), Time to Delamination (T260, T288, T300), Dimensional Stability, Solderability, Chemical Resistance, Metal Surfaces Cleanability, Pressure Cooker Test.

SAMPLE: Copper-Clad Laminate

TEST MATERIAL: TU-787LK

SPECIFICATION: IPC-4101E WAM1/130

TEST RESULTS: The specimens were tested by the indicated test methods within this report.
The actual detailed test results are enclosed.

DATE OF REPORT: 16 August 2022



SUMMARIZED TEST RESULTS:

Test Item	Thin	Thick
Peel Strength	Pass	Pass
Volume Resistivity	Pass	Pass
Surface Resistivity	Pass	Pass
Moisture Absorption	--	Pass
Dielectric Breakdown	--	Pass
Permittivity @ 1MHz	Pass	Pass
Loss Tangent @ 1MHz	Pass	Pass
Flexural Strength	--	Pass
Arc Resistance	Pass	Pass
Surface Resistivity	Pass	Pass
Thermal Stress	Pass	Pass
Electric Strength	Pass	Pass
Flammability	Pass	Pass
Glass Transition Temperature	--	Pass
Decomposition Temperature	--	Pass
Z-Axis CTE	--	Pass
Time to Delamination	--	Pass
Dimensional Stability	Pass	Pass
Solderability	--	Pass
Chemical Resistance	Report Only	Report Only
Metal Surface Cleanability	--	Report Only
Pressure Cooker Test	--	Report Only

Peel Strength

Reference:

IPC-TM-650 Method 2.4.8 Peel Strength of Metal Clad Laminates

IPC-TM-650 Method 3.4.8.3 Peel Strength of Metal Clad Laminates at Elevated Temperature

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 1 Peel Strength After Thermal Strength Thin

Side A Cross-Wise and Length-Wise Average	0.88	
Side B Cross-Wise and Length-Wise Average	0.90	
Requirement	≥ 0.80	Pass

Table 2 Peel Strength After Thermal Strength Thick

Side A Cross-Wise and Length-Wise Average	1.07	
Side B Cross-Wise and Length-Wise Average	1.06	
Requirement	≥ 1.05	Pass

Table 3 Peel Strength At Elevated Temperature Thin

Side A Cross-Wise and Length-Wise Average	0.85	
Side B Cross-Wise and Length-Wise Average	0.84	
Requirement	≥ 0.70	Pass

Table 4 Peel Strength At Elevated Temperature Thick

Side A Cross-Wise and Length-Wise Average	0.94	
Side B Cross-Wise and Length-Wise Average	0.95	
Requirement	≥ 0.70	Pass



Table 5 Peel Strength After Process Solutions Thin

Side A Cross-Wise and Length-Wise Average	0.84	
Side B Cross-Wise and Length-Wise Average	0.84	
Requirement	≥ 0.55	Pass

Table 6 Peel Strength After Process Solutions Thick

Side A Cross-Wise and Length-Wise Average	0.93	
Side B Cross-Wise and Length-Wise Average	0.92	
Requirement	≥ 0.80	Pass

Table 7 Peel Strength As Received Low Profile Copper Thin

Side A Cross-Wise and Length-Wise Average	0.81	
Side B Cross-Wise and Length-Wise Average	0.79	
Requirement	≥ 0.70	Pass

Table 8 Peel Strength As Received Low Profile Copper Thick

Side A Cross-Wise and Length-Wise Average	0.88	
Side B Cross-Wise and Length-Wise Average	0.90	
Requirement	≥ 0.70	Pass



Volume & Surface Resistivity

Reference:

IPC-TM-650 Method 2.5.17.1 Volume and Surface Resistivity of Dielectric Materials
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer
Printed Board

Results:

Table 9 Volume and Surface Resistivity Humidity Conditioning Thin

Volume Resistivity	Average of three specimens	4.30 E+09	
Requirement C-96/35/90		$\geq 1.00 \text{ E}+06$	Pass
Surface Resistivity	Average of three specimens	5.69 E+08	
Requirement C-96/35/90		$\geq 1.00 \text{ E}+04$	Pass

Table 10 Volume and Surface Resistivity At Elevated Temperature Thin

Volume Resistivity	Average of three specimens	3.76 E+08	
Requirement 125°C		$\geq 1.00 \text{ E}+03$	Pass
Surface Resistivity	Average of three specimens	8.24 E+07	
Requirement 125°C		$\geq 1.00 \text{ E}+03$	Pass

Table 11 Volume and Surface Resistivity Humidity Conditioning Thick

Volume Resistivity	Average of three specimens	5.04 E+09	
Requirement after moisture		1.00 E+04	Pass
Surface Resistivity	Average of three specimens	4.42 E+08	
Requirement after moisture		$\geq 1.00 \text{ E}+04$	Pass



Table 12 Volume and Surface Resistivity At Elevated Temperature Thick

Volume Resistivity Requirement 125°C	Average of three specimens	4.82 E+08 $\geq 1.00 \text{ E}+03$	Pass
Surface Resistivity Requirement 125°C	Average of three specimens	2.06 E+08 $\geq 1.00 \text{ E}+03$	Pass



Moisture Absorption

Reference:

IPC-TM-650 Method 2.6.2.1 Water Absorption of Metal Clad Plastic Laminates

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 13 Moisture Absorption Thick

Moisture Absorption	Average of three specimens	0.21	
Requirement		≤ 0.5	Pass

Dielectric Breakdown

Reference:

IPC-TM-650 Method 2.5.6 Dielectric Breakdown

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 14 Dielectric Breakdown

Moisture Absorption	Average of four specimens	44 +	
Requirement		≥ 40	Pass



Permittivity and Loss Tangent @ 1 MHz

Reference:

IPC-TM-650 Method 2.5.5.9 Permittivity and Loss Tangent, Parallel Plate 1 MHz to 1.5 MHz

IPC-TM-650 Method 2.5.5.15 Permittivity and Loss Tangent, SPDR 1 GHz

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 15 Permittivity and Loss Tangent

Permittivity @ 1 MHz	Average of three specimens	4.14	
Requirement Thin		≤ 5.4	Pass
Loss Tangent @ 1 MHz	Average of three specimens	0.006	
Requirement Thin		≤ 0.035	Pass
Permittivity @ 1 MHz	Average of three specimens	4.30	
Requirement Thick		≤ 5.4	Pass
Loss Tangent @ 1 MHz	Average of three specimens	0.009	
Requirement Thick		≤ 0.035	Pass
Permittivity @ 1 GHz	Average of three specimens	3.93	
No Requirement Thin			
Loss Tangent @ 1 GHz	Average of three specimens	0.009	
No Requirement Thin			
Permittivity @ 1 GHz No	Average of three specimens	4.50	
No Requirement Thick			
Loss Tangent @ 1 GHz	Average of three specimens	0.009	
No Requirement Thick			

Flexural Strength

Reference:

IPC-TM-650 Method 2.4.4 Flexural Strength of Laminates at Ambient Temperature
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer
Printed Board

Results:

Table 16 Flexural Strength

Flexural Strength Length Direction Requirement	Average of two specimens	476 ≥ 415	Pass
Flexural Strength Cross Direction Requirement	Average of two specimens	450 ≥ 345	Pass

Arc Resistance

Reference:

IPC-TM-650 Method 2.5.1 Arc Resistance of Printed Wiring Material
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 17 Arc Resistance

Arc Resistance Thin Requirement	Average of three specimens	181 ≥ 60	Pass
Arc Resistance Thick Requirement	Average of three specimens	181 ≥ 60	Pass

Thermal Stress

Reference:

IPC-TM-650 Method 2.4.13.1 Thermal Stress of Laminates

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 18 Thermal Stress

Thermal Stress Thin Etched A Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thin Etched B Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thick Etched A Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thick Etched B Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thin Un-Etched A Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thin Un-Etched B Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thick Un-Etched A Side	No obvious blister, delamination or damage	Pass
Thermal Stress Thick Un-Etched B Side	No obvious blister, delamination or damage	Pass

Electric Strength

Reference:

IPC-TM-650 Method 2.5.6.2 Electric Strength

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 19 Electric Strength

Electric Strength Thin Requirement	Average of three specimens	83	≥ 30	Pass
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Flammability Vertical Burning

Reference:

UL94 Section 8 50W (20mm) Vertical Burning Test; V-0, V-1, V-2

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 20 Vertical Burning Test Thin

The specimens were tested by the methods given above.

The flammability Classification Condition A of specimens is V-0

The flammability Classification Condition A of specimens is V-0

The specimens pass.

Table 21 Vertical Burning Test Thick

The specimens were tested by the methods given above.

The flammability Classification Condition A of specimens is V-0

The flammability Classification Condition B of specimens is V-0

The specimens pass.



Glass Transition Temperature

Reference:

IPC-TM-650 Method 2.4.25 Glass Transition Temperature and Cure Factor by DSC
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer
Printed Boards

Results:

Table 22 Glass Transition Temperature

Glass Transition Temperature	172°C	
Requirement	≥ 170	Pass

Decomposition Temperature

Reference:

IPC-TM-650 Method 2.4.24.6 Decomposition Temperature of Laminate Material Using TGA
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed
Board

Results:

Table 23 Decomposition Temperature

Glass Transition Temperature 5% Weight Loss	384°C	
Requirement	≥ 340	Pass



Z-Axis CTE (TMA)

Reference:

IPC-TM-650 Method 2.4.24.6 Decomposition Temperature of Laminate Material Using TGA
IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed
Board

Results:

Table 24 Z-Axis CTE (TMA)

Z-Axis CTE Alpha 1	Average of two specimens	24	≤ 60	Pass
Z-Axis CTE Alpha 2	Average of two specimens	239	≤ 300	Pass
Z-Axis CTE 50-260	Average of two specimens	2.8	≤ 3.0	Pass



Time to Delamination

Reference:

IPC-TM-650 Method 2.4.24.1 Time to Delamination (TMA Method)

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 25 Time to Delamination (TMA)

Delamination T260	Average of two specimens	> 60	
	Requirement	≥ 30	Pass
Delamination T288	Average of two specimens	> 45	
	Requirement	≥ 15	Pass
Delamination T300	Average of two specimens	> 4	
	Requirement	≥ 2	Pass



Dimensional Stability

Reference:

IPC-TM-650 Method 2.4.39 Dimensional Stability, Glass Reinforced Thin Laminates

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 26 Dimensional Stability Thin

Dimensional Stability Bake	Average of three specimens		
	Machine direction	-0.05	
	Cross direction	-0.07	
	Requirement	-0.3 to +0.3	Pass
Dimensional Stability Stress	Average of three specimens		
	Machine direction	-0.03	
	Cross direction	-0.06	
	Requirement	-0.3 to +0.3	Pass

Table 27 Dimensional Stability Thick

Dimensional Stability Bake	Average of three specimens		
	Machine direction	-0.06	
	Cross direction	-0.08	
	Requirement	-0.3 to +0.3	Pass
Dimensional Stability Stress	Average of three specimens		
	Machine direction	-0.02	
	Cross direction	-0.06	
	Requirement	-0.3 to +0.3	Pass



Solderability (Edge Dip Test)

Reference:

IPC-J-STD-003C; Method 4.2.1 Edge Dip Test

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 28 Solderability (TMA)

Solderability Thin	Sample surface exhibited good wetting	Pass
Solderability Thick	Sample surface exhibited good wetting	Pass

Chemical Resistance

Reference:

IPC-TM-650 Method 2.3.4.2 Chemical Resistance of Laminates, Prepreg and Coated Foil Products by Solvent Exposure.

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 29 Chemical Resistance

Chemical Resistance Thin	Three specimens		
Requirement	Appearance after bake	No change	Pass
Requirement	Appearance after solvent	No change	Pass
Chemical Resistance Thick	Three specimens		
Requirement	Appearance after bake	No change	Pass
Requirement	Appearance after solvent	No change	Pass



Metal Surface Cleanability

Reference:

IPC-TM-650 Method 2.3.1.1 Chemical Cleaning of Metal-Clad Laminate

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 30 Metal Surface Cleanability

Metal Surface Cleanability	Three specimens	
Requirement	The metal cladding on the test specimen shall be cleaned to a uniform matte finish. Deionized or distilled water poured on the surface does not bead or form puddles.	Pass

Pressure Cooker Test

Reference:

IPC-TM-650 Method 2.6.16 Pressure Vessel Method for Glass Epoxy Laminate Integrity

IPC-4101E WAM1/130 Specification for Base Materials for Rigid and Multilayer Printed Board

Results:

Table 31 Pressure Cooker Test

Pressure Cooker Test	Five specimens	
Requirement	The samples shall have no measles, blisters or surface erosion	Pass

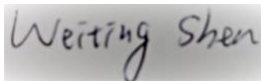
CERTIFICATE OF CONFORMANCE

The TAWIAN UNION TECHNOLOGY CORPORATION (TUC) certifies that the test equipment used complies with the requirements of correlation criterion and that data contained in this report is accurate within the tolerance limitation of the equipment.

The report is invalid without the signature of the reviewer and the approver.

Reviewed by:

Approved by:



Weiting Shen

QA Engineer

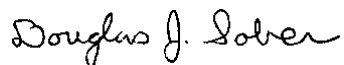
16 August 2022



Money Wang

QA Manager

16 August 2022



For IPC

16 August 2022